

TSMC 98-684/685/688  
Serial Number 09/418,031



1765  
#7/A  
4/19/01

### AMENDMENTS AND RESPONSE TO OFFICE ACTION

**TO:** COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D. C. 20231

**FROM:** George O. Saile (Reg. No. 19,572)  
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Poughkeepsie, NY 12603

**DATE:** 09 April 2001

**REF:** APPLICANT : Jang et al.  
SERIAL NO. : 09/418,031  
ART UNIT : 1765  
FILING DATE : 14 October 1999  
ATTY NO. : TSMC 98-684/685/688  
EXAMINER : L. Vinh  
TITLE : Damascene Method Employing Composite Etch Stop Layer

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Sir:

In response to an office action mailed on 12 January 2001, please consider the following amendments and remarks pertaining to the above referenced application.

### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class mail in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D. C. 20231 on 11 April 2001.

Stephen B. Ackerman  
Name 37,761

[Signature]  
Signature

4/11/01  
Date

## AMENDMENTS

### *In The Claims*

Please amend claims 11, 19 and 20 as follows:

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A<sub>1</sub> 11. (amended) The method of Claim 4 wherein the said conductor material is copper metal.

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A<sub>2</sub> 19. (amended) The method of Claim 14 wherein the conductor material employed to fill the interconnection trench is copper metal.

20. (amended) The method of Claim 14 wherein the barrier metal layer is formed employing tantalum nitride (TaN).

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